

N-Channel Super Junction Power MOSFET IV

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

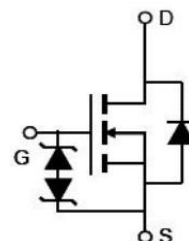
Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

| | | |
|------------------------|-----|----|
| $V_{DS\ min@T_{jmax}}$ | 710 | V |
| $R_{DS(ON)TYP.}$ | 410 | mΩ |
| I_D | 9 | A |
| Q_g | 12 | nC |



Schematic diagram

Package Marking And Ordering Information

| Device | Device Package | Marking |
|------------|----------------|------------|
| NCE65N460F | TO-220F-3L | NCE65N460F |



TO-220F

Table 1. Absolute Maximum Ratings ($T_c=25^{\circ}\text{C}$)

| Parameter | Symbol | Value | Unit |
|---|-----------------|------------|-----------------------|
| Drain-Source Voltage ($V_{GS}=0V$) | V_{DS} | 650 | V |
| Gate-Source Voltage ($V_{DS}=0V$), AC ($f>1\text{ Hz}$) | V_{GS} | ± 30 | V |
| Gate-Source Voltage ($V_{DS}=0V$), DC | V_{GS} | ± 20 | V |
| Continuous Drain Current at $T_c=25^{\circ}\text{C}$ | $I_D(DC)$ | 9 | A |
| Continuous Drain Current at $T_c=100^{\circ}\text{C}$ | $I_D(DC)$ | 6.3 | A |
| Pulsed drain current (Note 1) | $I_{DM}(pulse)$ | 27 | A |
| Maximum Power Dissipation($T_c=25^{\circ}\text{C}$) | P_D | 31.9 | W |
| Derate above 25°C | | 0.21 | W/ $^{\circ}\text{C}$ |
| Single pulse avalanche current (Note 2) | I_{AS} | 2.5 | A |
| Reverse diode dv/dt , $V_{DS} \leq 480\text{ V}$, $I_{SD} < I_D$ | dv/dt | 15 | V/ns |
| Drain Source voltage slope, $V_{DS} \leq 480\text{ V}$ | dv/dt | 50 | V/ns |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55...+175 | $^{\circ}\text{C}$ |

Table 2. Thermal Characteristic

| Parameter | Symbol | Value | Unit |
|---|------------|-------|-----------------------------|
| Thermal Resistance, Junction-to-Case (Maximum) | R_{thJC} | 4.70 | $^{\circ}\text{C}/\text{W}$ |
| Thermal Resistance, Junction-to-Ambient (Maximum) | R_{thJA} | 62 | $^{\circ}\text{C}/\text{W}$ |

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|---------------------|--|-----|------|------|------|
| On/off states | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250uA | 650 | | | V |
| Zero Gate Voltage Drain Current(Tc=25℃) | I _{DSS} | V _{DS} =650V,V _{GS} =0V | | | 1 | μA |
| Zero Gate Voltage Drain Current(Tc=125℃) | I _{DSS} | V _{DS} =650V,V _{GS} =0V | | | 100 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±20V,V _{DS} =0V | | | ±200 | nA |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =250uA | 3 | 3.5 | 4 | V |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =10V, I _D =4.5A | | 410 | 460 | mΩ |
| Dynamic Characteristics | | | | | | |
| Gate Resistance | R _g | F=1MHZ, D-S short | | 40 | | Ω |
| Input Capacitance | C _{iss} | V _{DS} =50V,V _{GS} =0V, F=1MHz | | 530 | | pF |
| Output Capacitance | C _{oss} | | | 25 | | pF |
| Reverse Transfer Capacitance | C _{rss} | | | 5.6 | | pF |
| Total Gate Charge | Q _g | V _{DS} =380V,I _D =4.5A, V _{GS} =10V | | 12 | | nC |
| Gate-Source Charge | Q _{gs} | | | 5.7 | | nC |
| Gate-Drain Charge | Q _{gd} | | | 1.4 | | nC |
| Gate plateau voltage | V _{gp} | | | 5.6 | | V |
| Switching times | | | | | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =400V,I _D =4.5A, R _G =4Ω,V _{GS} =10V | | 9 | | nS |
| Turn-on Rise Time | t _r | | | 6 | | nS |
| Turn-Off Delay Time | t _{d(off)} | | | 52 | | nS |
| Turn-Off Fall Time | t _f | | | 8 | | nS |
| Source- Drain Diode Characteristics | | | | | | |
| Source-drain current(Body Diode) | I _{SD} | T _C =25℃ | | | 9 | A |
| Pulsed-Source-drain current(Body Diode) | I _{SDM} | | | | 27 | A |
| Forward on voltage | V _{SD} | T _j =25℃,I _{SD} =9A,V _{GS} =0V | | 0.9 | 1.2 | V |
| Reverse Recovery Time | t _{rr} | T _j =25℃,I _F =4.5A, di/dt=100A/μs | | 195 | | nS |
| Reverse Recovery Charge | Q _{rr} | | | 1.36 | | uC |
| Peak reverse recovery current | I _{rrm} | | | 14 | | A |

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. $T_j=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, R_G=25\Omega$

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Output characteristics

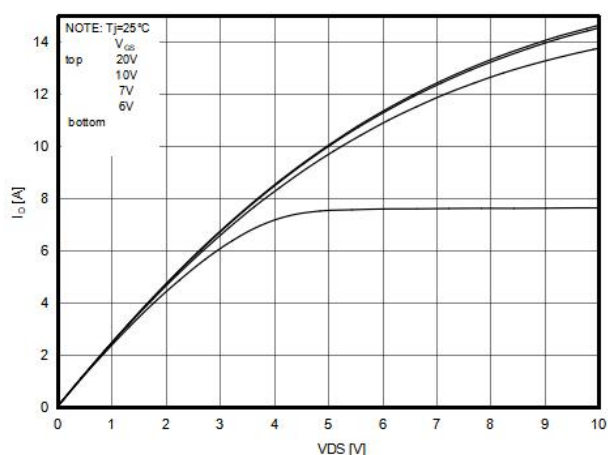


Figure2. Transfer characteristics

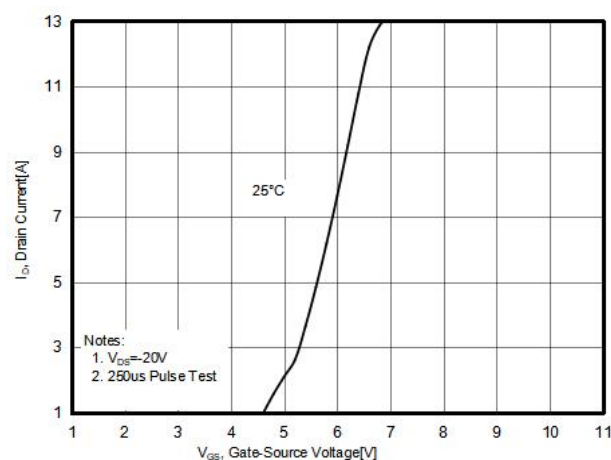


Figure3. $R_{DS(ON)}$ vs Junction Temperature

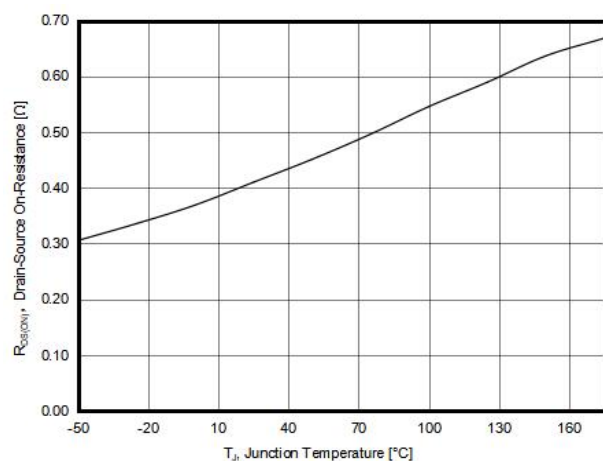


Figure4. BV_{DSS} vs Junction Temperature

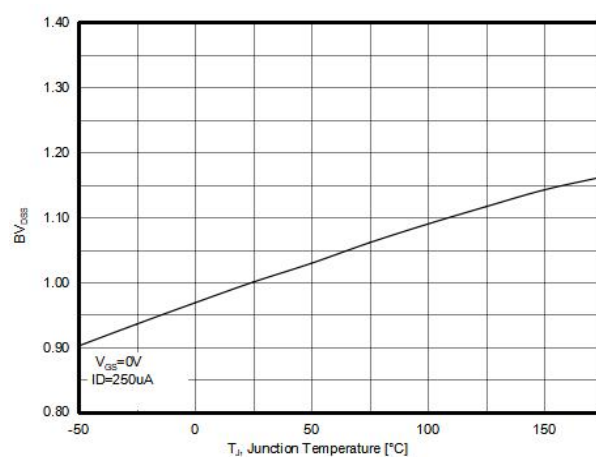


Figure5. Maximum I_D vs Junction Temperature

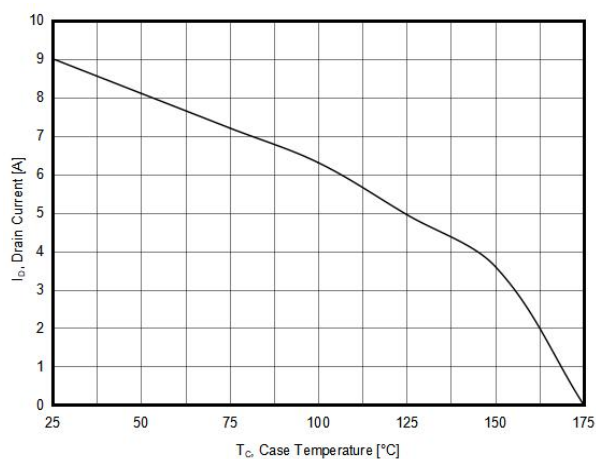


Figure6. Gate charge waveforms

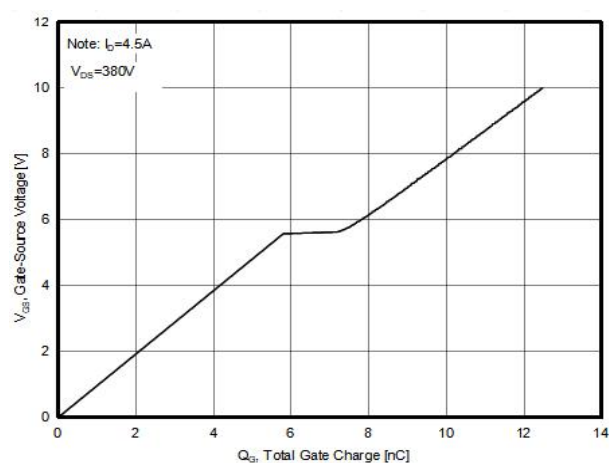


Figure7. Static drain-source on resistance

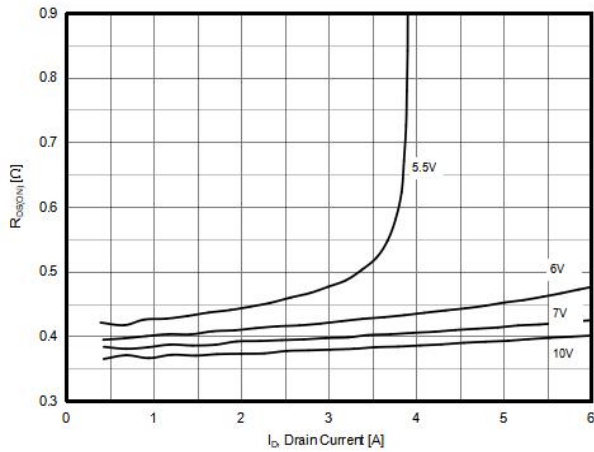


Figure8. Source-Drain Diode Forward Voltage

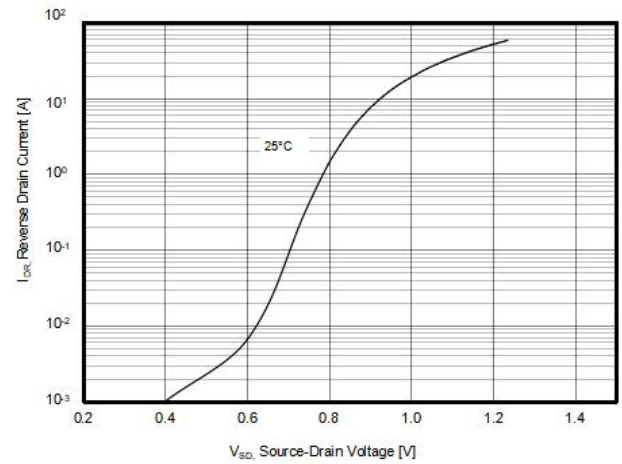


Figure9. Capacitance

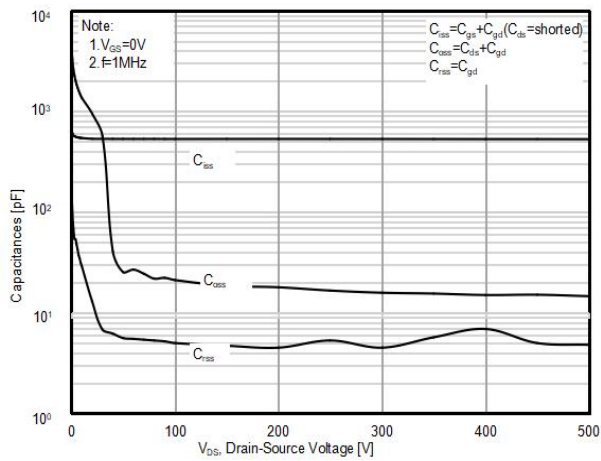
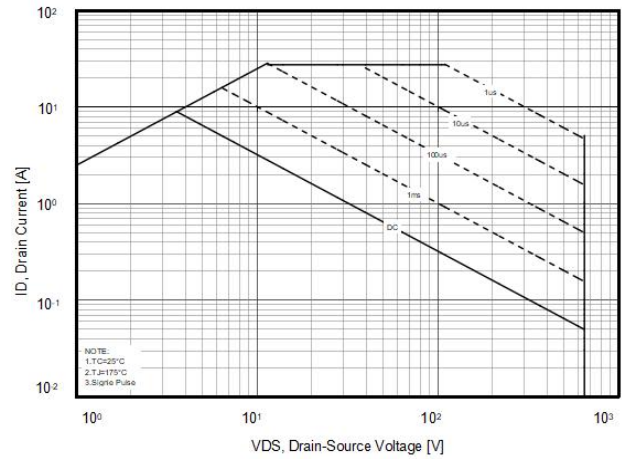
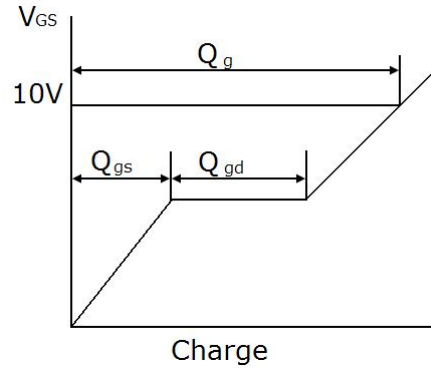


Figure10. Safe operating area

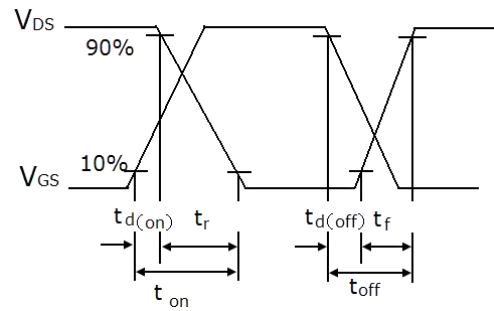


Test circuit

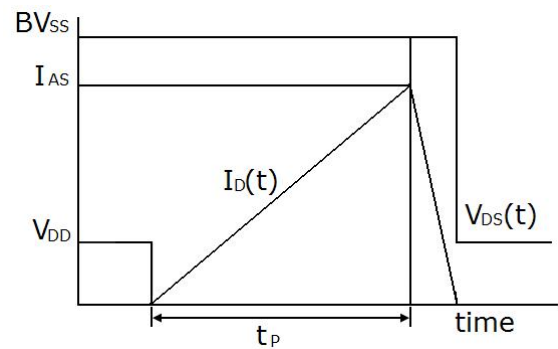
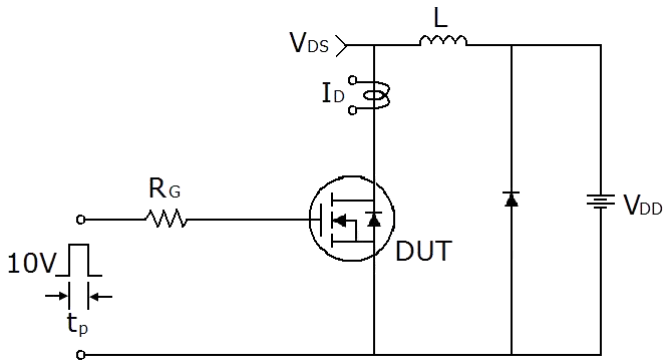
1) Gate charge test circuit & Waveform



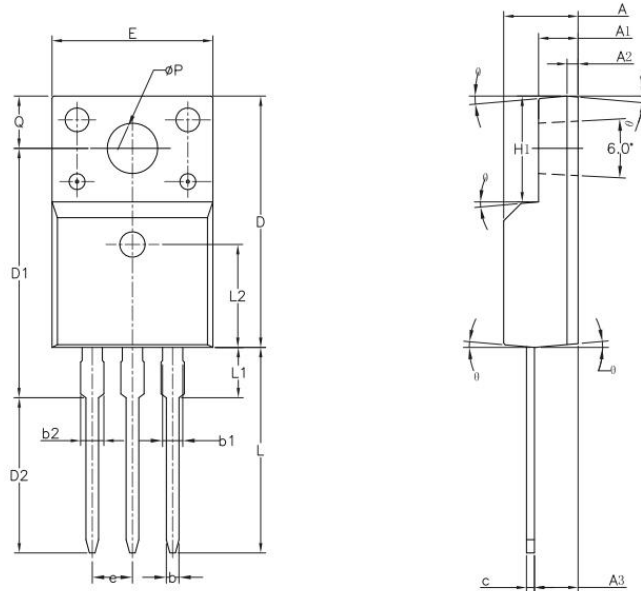
2) Switch Time Test Circuit:



3) Unclamped Inductive Switching Test Circuit & Waveforms



TO-220F-P Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.50 | 4.83 | 0.177 | 0.190 |
| A1 | 2.34 | 2.74 | 0.092 | 0.108 |
| A2 | 0.70 REF | | 0.028 REF | |
| A3 | 2.56 | 2.93 | 0.101 | 0.115 |
| b | 0.70 | 0.90 | 0.028 | 0.035 |
| b1 | 1.18 | 1.38 | 0.046 | 0.054 |
| b2 | -- | 1.47 | -- | 0.058 |
| c | 0.45 | 0.60 | 0.018 | 0.024 |
| D | 15.67 | 16.07 | 0.616 | 0.631 |
| D1 | 15.55 | 15.95 | 0.611 | 0.627 |
| D2 | 9.60 | 10.00 | 0.377 | 0.393 |
| E | 9.96 | 10.36 | 0.391 | 0.407 |
| e | 2.54 BSC | | 0.100 BSC | |
| H1 | 6.48 | 6.88 | 0.255 | 0.270 |
| L | 12.68 | 13.28 | 0.498 | 0.522 |
| L1 | -- | 3.50 | -- | 0.138 |
| L2 | 6.50 REF | | 0.255 REF | |
| ∅ P | 3.08 | 3.28 | 0.121 | 0.129 |
| Q | 3.20 | 3.40 | 0.126 | 0.134 |
| θ1 | 1.0° | 5.0° | 1.00° | 5.00° |

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